

Fig. 1

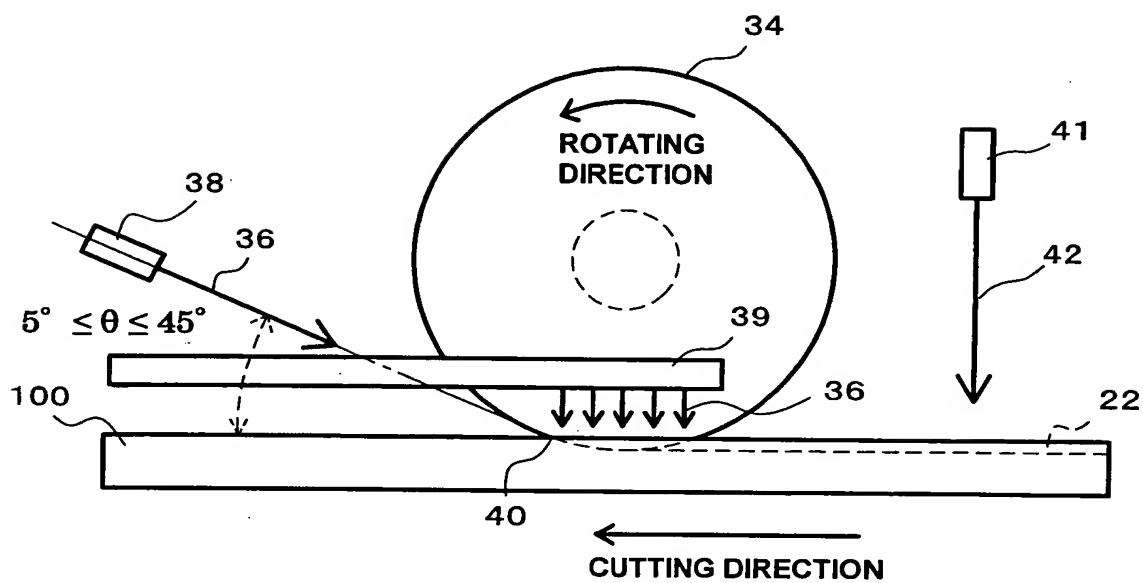


Fig. 2A

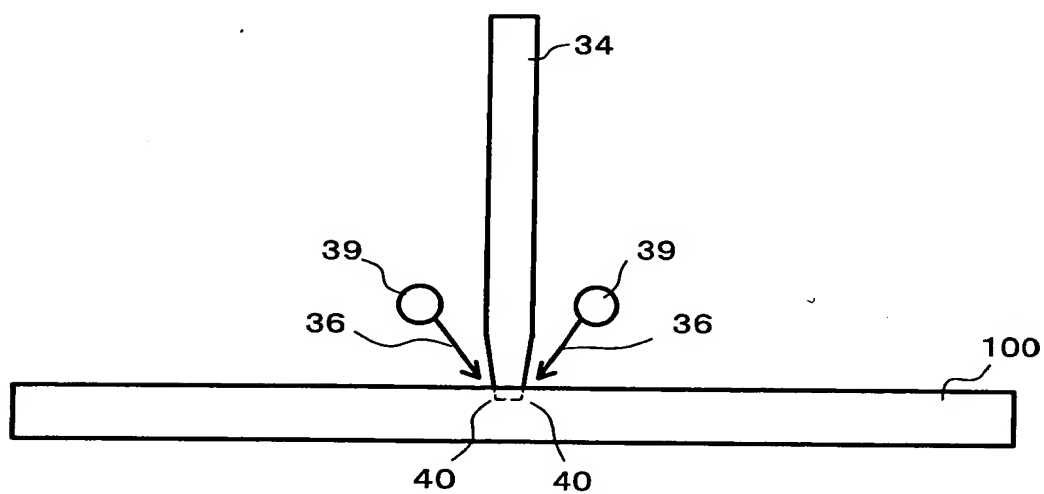


Fig. 2B

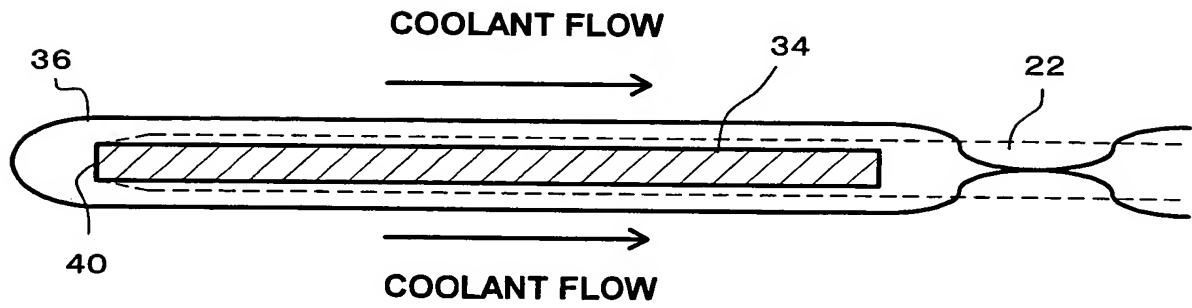


Fig. 3A

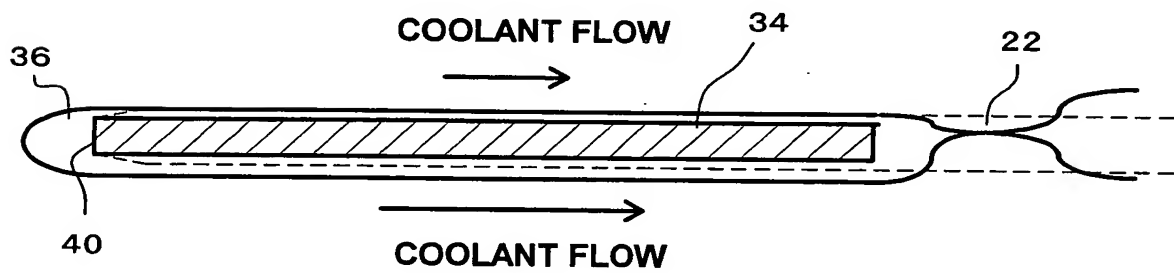


Fig. 3B

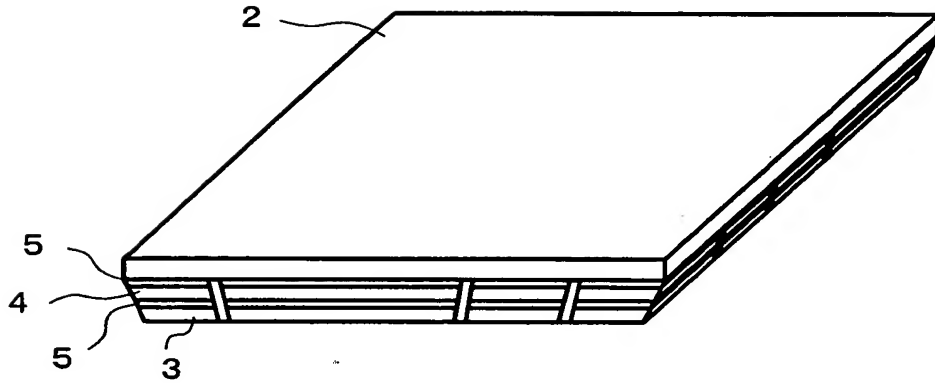


Fig. 4A

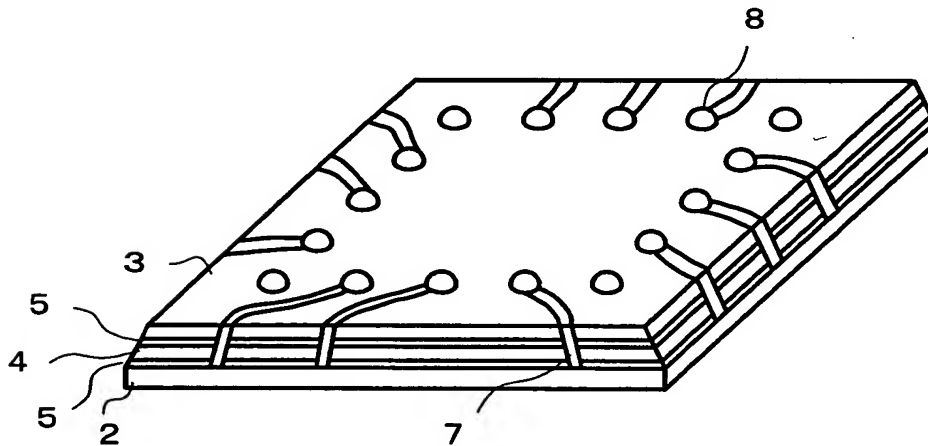


Fig. 4B

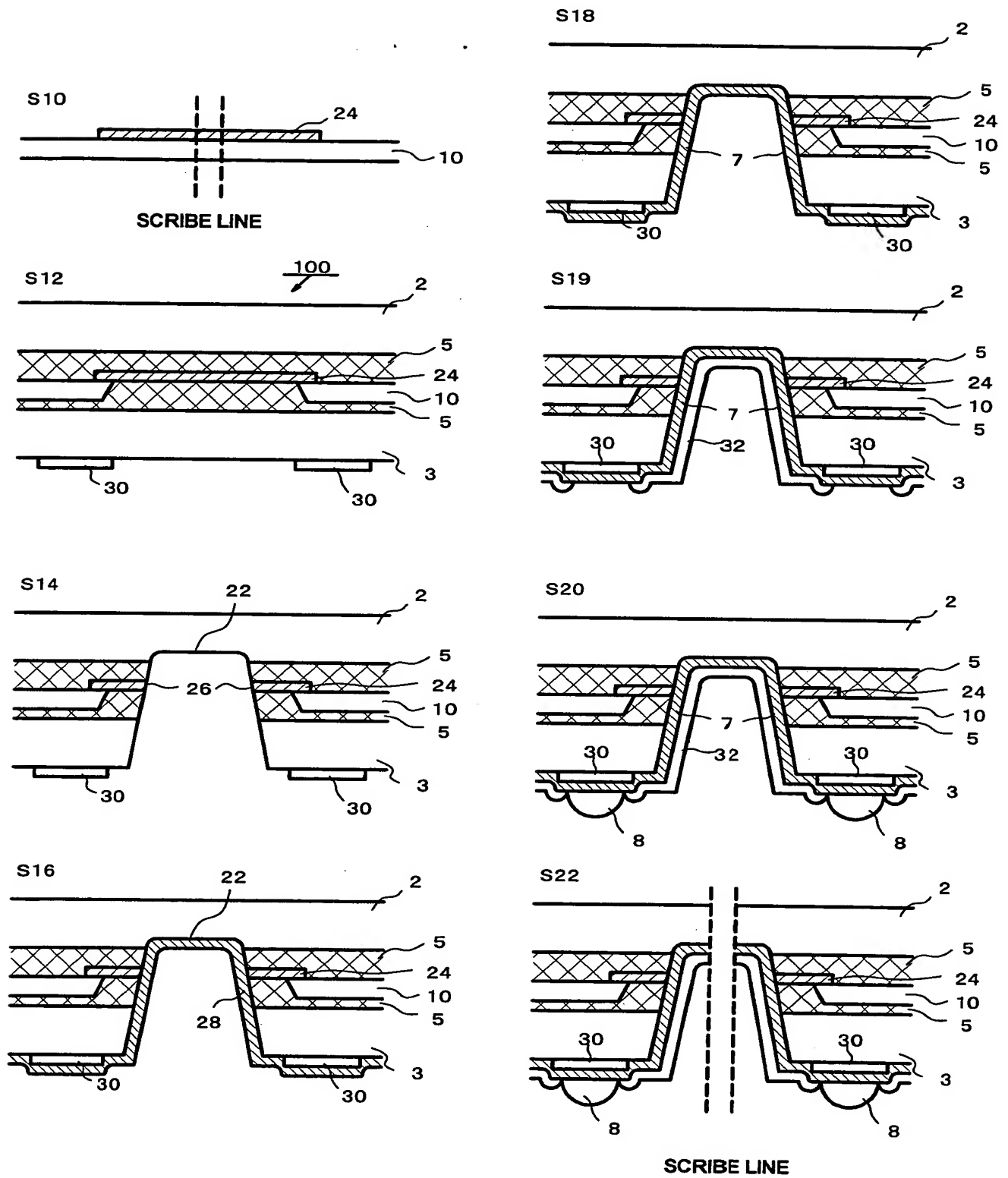


Fig. 5

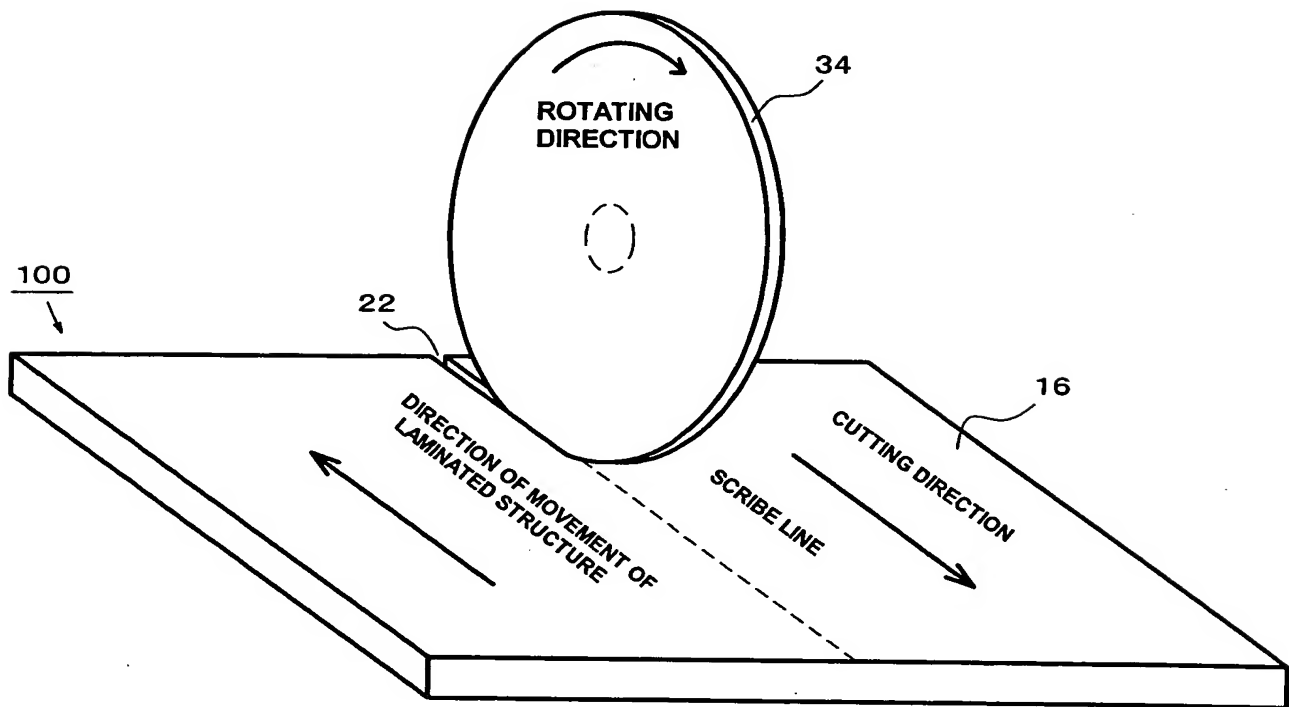


Fig. 6



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- ShellOP
- ShellBGA

Overview | Process

On this page you can view the process flow of Shellcase's ShellOP product.

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PRODUCTS

Index

[Step A: Passivation and Pad Extension Layers](#)

[Step B: Glass 1 Attachment](#)

[Step C: Backside Silicon Grinding & Scribe Line Etch](#)

[Step D: Glass 2 Attachment](#)

[Step E: Compliant Layer Formation](#)

[Step F: Notch](#)

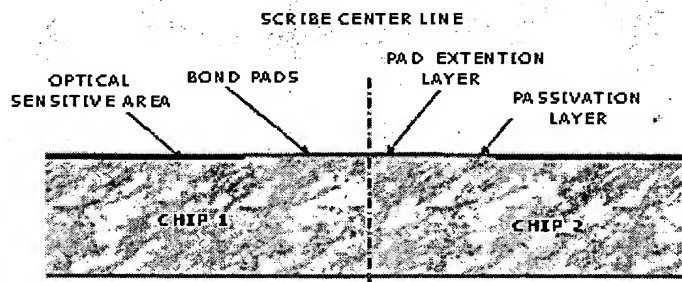
[Step G: External Lead Formation](#)

[Step H: External Passivation](#)

[Step I: BGA Formation](#)

[Step J: Dicing](#)

Step A: Passivation and Pad Extension Layers

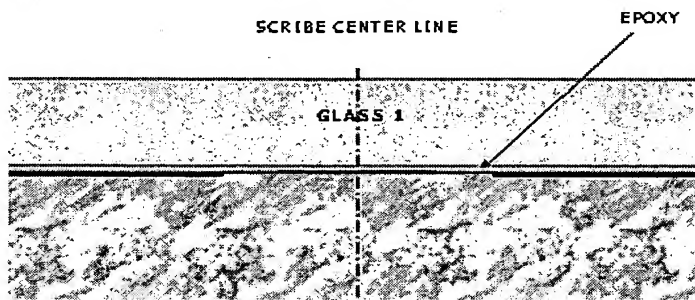


A B C D E F G H I J

Back to Top ▲

Back ◀ Next ▶

Step B: Glass 1 Attachment



A B C D E F G H I J

[Back to Top](#)[Back](#) [Next](#)**Step C: Backside Silicon Grinding & Scribe Line Etch**

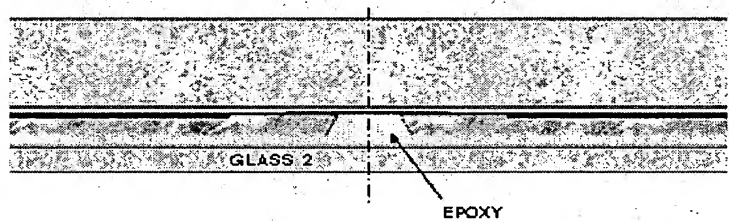
SCRIBE CENTER LINE



A B C D E F G H I J

[Back to Top](#)[Back](#) [Next](#)**Step D: Glass 2 Attachment**

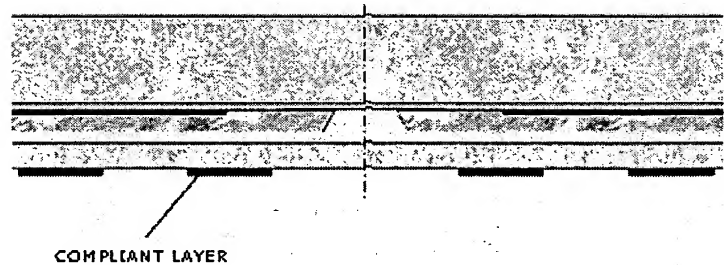
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A B C D E F G H I J

[Back to Top](#)[Back](#) [Next](#)**Step E: Compliant Layer Formation**

SCRIBE CENTER LINE

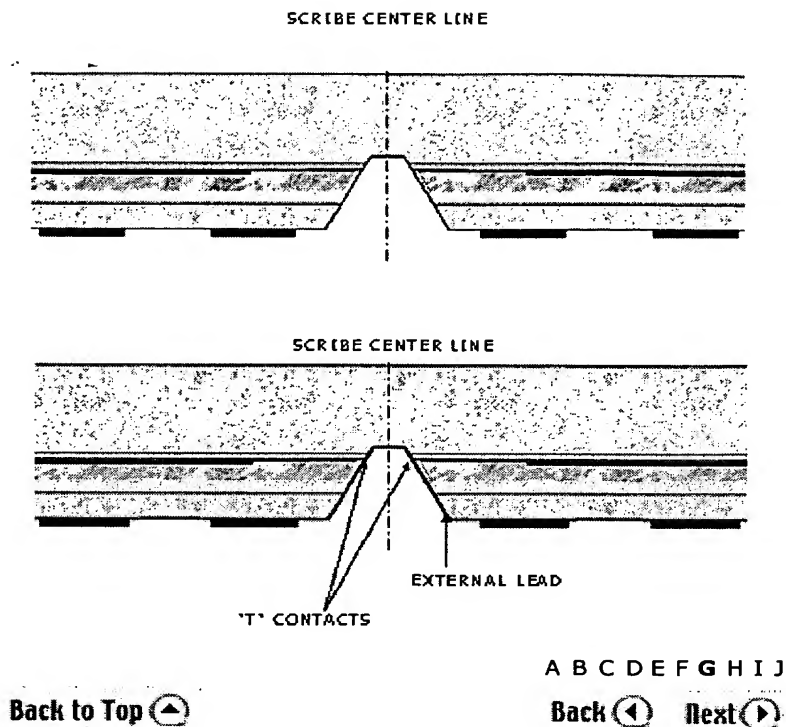


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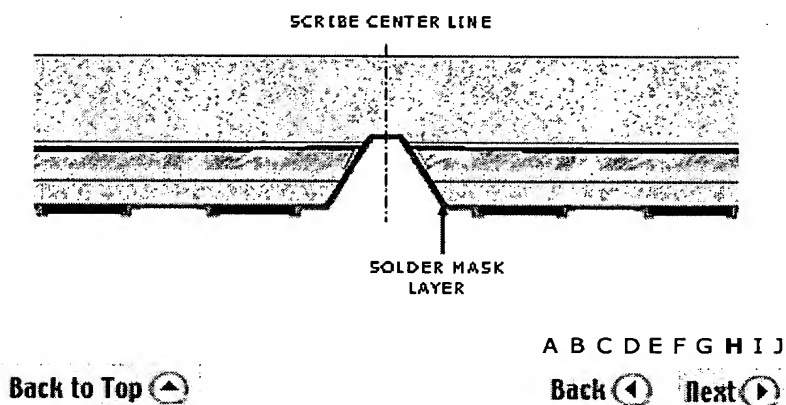
[Back to Top](#)[Back](#) [Next](#)**Step F: Notch**

A B C D E F G H I J

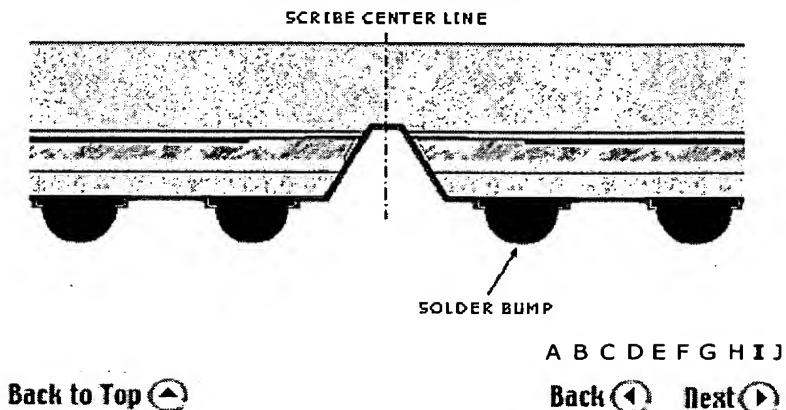
[Back to Top](#)[Back](#) [Next](#)**Step G: External Lead Formation**



Step H: External Passivation

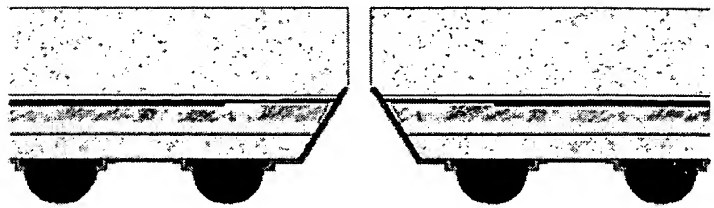


Step I: BGA Formation




Step J: Dicing

SCRIBE CENTER LINE



Back to Top 

A B C D E F G H I J

Back  Next 